

An IATF 16949, ISO9001 and ISO 14001/ISO 45001 Certified Company





3.0Amp Shottky Diodes

20 ~ 200V, 3Amp



SR320 ~ SR3200

DO-201AD Leaded Plastic Package RoHS compliant

FEATURES:

- 1. Fast switching speed
- 2. Low forward voltage
- 3. Low power high efficiency
- 4. High surge capability
- 5. High temperature soldering guaranteed, 250°C/10 seconds,0.373"(9.5mm)lead length

ABSOLUTE MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified, Single phase, half wave, 60Hz, resistive or inductive load, For capacitive load derate current by 20%

PARAMETER	SYMBOL	SR3 20	SR3 40	SR3 60	SR3 80	SR3 100	SR3 150	SR3 200	UNITS
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	20	40	60	80	100	150	200	V
Maximum RMS Bridge Input Voltage	V_{RMS}	14	28	42	56	70	105	140	V
Maximum DC Blocking Voltage	V_{DC}	20	40	60	80	100	150	200	V
Maximum Average Forward Rectified Currel figure 1 at T _L =100° C	nt I _(AV)				3.0				А
Peak Forward Surge Current 8.3ms Single I Sine-Wave Super Imposed on Rated Load (JEDEC Method)	lalf IFSM	80				А			
Maximum Forward Voltage at 3.0A DC	VF	0).55	0.7		0.85		0.95	V
Maximum DC Reverse Current at T _J =2!	5°C IR			0.5			0	.1	mA
Rated DC Blocking Voltage per element T _J =10			20		1	0	1	.5	ША
Typical Thermal Resistance	$R_{\theta JA}$				55				°C/W
Typical Thermal Resistance	$R_{\theta JC}$	16				°C/W			
Operating Temperature Range	Tj	-55 to +150					°C		
Storage Temperature Range	Tstg	-55 to +150				°C			

Notes:

- 1. Pulse test:300µs pulse width,1% duty cycle.
- 2. Thermal Resistance from junction to Ambient at .375"(9.5mm)lead length, P.C.board mounted.

SR320 ~ SR3200

Rev0_02042024YF







An IATF 16949, ISO9001 and ISO 14001/ISO 45001 Certified Company

TYPICAL CHARACTERISTIC CURVES

Fig.1 FORWARD CURRENTDERATING

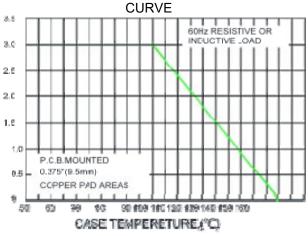
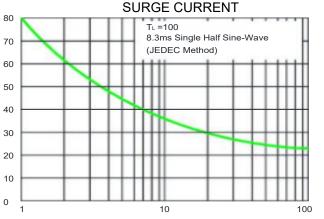


FIG. 2 MAXIMUM NON-REPETITIVE PEAKFORWARD



NUMBER OF CYCLES AT 60 Hz
FIG 3-TYPICAL INSTANTANEOUSFORWARD
CHARACTERISTICS

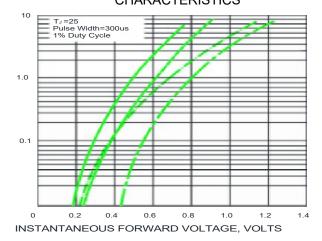
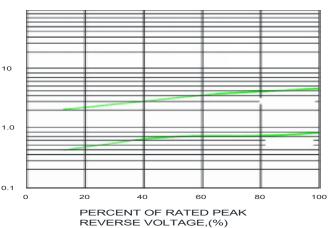
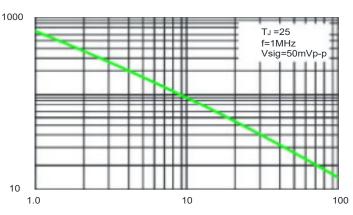


FIG. 4 TYPICAL REVERSE CHARACTERISTICS



F1G.5 TYPICAL JUNCTION CAPACITANCE



REVRESE VOLTAGE, VOLTS



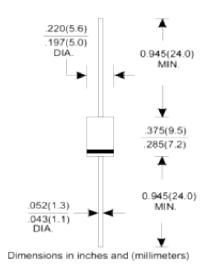






PACKAGE DETAILS

Package Outline: DO-201AD



Mechanical Data

Case: Transfer molded plastic

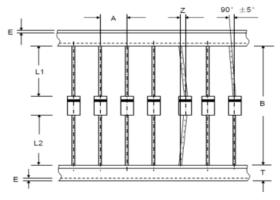
Epoxy: UL 94V-0 rate flame retardant

Lead :Solder plated, solderable per MIL-STD-750 method 2026

Polarity: Color band denotes cathode end

Weight: 0.042ounce, 1.19 gram

Taping Specifications



	Component Pitch A Component Outline	Inner Tape Pitch B	Cumulative	
	±0.5mm		Tolerance	
DO-201AD(DO-27)	10.0mm	52.4mm	2.0mm/20pitch	

Item	Symbol	Specifications(mm)	Specifications(inch)		
Component Alignment	Z	1.2 max	0.048 max		
Tape width	Т	6.0 +/-0.4	0.236 +/-0.016		
Exposed adhesive	E	0.8 max	0.032 max		
Body eccentricity	IL1-L2I	1.0 max	0.040 max		







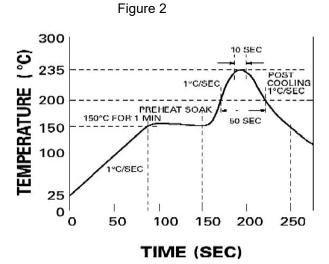
An IATF 16949, ISO9001 and ISO 14001/ISO 45001 Certified Company

Recommended Reflow Solder Profiles

The recommended reflow solder profiles for Pb and Pb-free devices are shown below.

Figure 1 shows the recommended solder profile for devices that have Pb-free terminal plating, and where a Pb-free solder is used.

Figure 2 shows the recommended solder profile for devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with a leaded solder.



Reflow profiles in tabular form

Profile Feature	Sn-Pb System	Pb-Free System
Average Ramp-Up Rate	~3°C/second	~3°C/second
Preheat		
– Temperature Range	150-170°C	150-200°C
– Time	60-180 seconds	60-180 seconds
Time maintained above:		
– Temperature	200°C	217°C
– Time	30-50 seconds	60-150 seconds
Peak Temperature	235°C	260°C max.
Time within +0 -5°C of actual Peak	10 seconds	40 seconds
Ramp-Down Rate	3°C/second max.	6°C/second max.



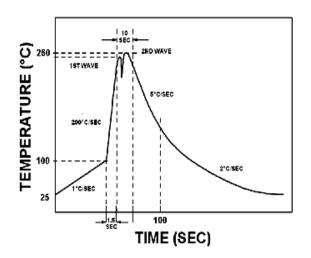




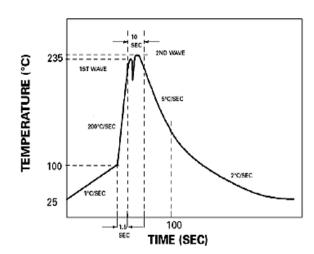
An IATF 16949, ISO9001 and ISO 14001/ISO 45001 Certified Company

Recommended Wave Solder Profiles

The Recommended solder Profile For Devices with Pb-free terminal plating where a Pb-free solder is used



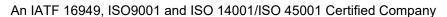
The Recommended solder Profile For Devices with Pbfree terminal plating used with leaded solder, or for devices with leaded terminal plating used with leaded solder



Wave Profiles in Tabular Form

Profile Feature	Sn-Pb System	Pb-free System		
Average Ramp-Up Rate	~200°C/second	~200°C/second		
Heating rate during preheat	Typical 1-2, Max 4°C/sec	Typical 1-2, Max 4°C/Sec		
Final preheat Temperature	Within 125°C of Solder Temp	Within 125°C of Solder Temp		
Peak Temperature	235°C	260°C max.		
Time within +0 -5°C of actual Peak	10 seconds	10 seconds		
Ramp-Down Rate	5°C/second max.	5°C/second max.		









Recommended Product Storage Environment for Discrete Semiconductor Devices

This storage environment assumes that the Diodes and transistors are packed properly inside the original packing supplied by CDIL.

- Temperature 5 °C to 30 °C
- Humidity between 40 to 70 %RH
- Air should be clean.
- Avoid harmful gas or dust.
- Avoid outdoor exposure or storage in areas subject to rain or water spraying .
- Avoid storage in areas subject to corrosive gas or dust. Product shall not be stored in areas exposed to direct sunlight.
- Avoid rapid change of temperature.
- Avoid condensation.
- Mechanical stress such as vibration and impact shall be avoided.
- The product shall not be placed directly on the floor.
- The product shall be stored on a plane area. They should not be turned upside dawn. They should not be placed against the wall.

Shelf Life of CDIL Products

The shelf life of products is the period from product manufacture to shipment to customers. The product can be unconditionally shipped within this period. The period is defined as 2 years.

If products are stored longer than the shelf life of 2 years the products shall be subjected to quality check as per CDIL quality procedure.

The products are further warranted for another one year after the date of shipment subject to the above conditions in CDIL original packing.

Floor Life of CDIL Products and MSL Level

When the products are opened from the original packing, the floor life will start.

For this, the following JEDEC table may be referred:

JEDEC MSL Level					
Level	Time	Condition			
1	Unlimited	≤30 °C / 85% RH			
2	1 Year	≤30 °C / 60% RH			
2a	4 Weeks	≤30 °C / 60% RH			
3	168 Hours	≤30 °C / 60% RH			
4	72 Hours	≤30 °C / 60% RH			
5	48 Hours	≤30 °C / 60% RH			
5a	24 Hours	≤30 °C / 60% RH			
6	Time on Label(TOL)	≤30 °C / 60% RH			









Customer Notes

Component Disposal Instructions

- 1. CDIL Semiconductor Devices are RoHS compliant, customers are requested to please dispose as per prevailing Environmental Legislation of their Country.
- 2. In Europe, please dispose as per EU Directive 2002/96/EC on Waste Electrical and Electronic Equipment (WEEE).

Disclaimer

The product information and the selection guides facilitate selection of the CDIL's Semiconductor Device(s) best suited for application in your product(s) as per your requirement. It is recommended that you completely review our Data Sheet(s) so as to confirm that the Device(s) meet functionality parameters for your application. The information furnished in the Data Sheet and on the CDIL Web Site/CD are believed to be accurate and reliable. CDIL however, does not assume responsibility for inaccuracies or incomplete information. Furthermore, CDIL does not assume liability whatsoever, arising out of the application or use of any CDIL product; neither does it convey any license under its patent rights nor rights of others. These products are not designed for use in life saving/support appliances or systems. CDIL customers selling these products (either as individual Semiconductor Devices or incorporated in their end products), in any life saving/support appliances or systems or applications do so at their own risk and CDIL will not be responsible for any damages resulting from such sale(s).

CDIL strives for continuous improvement and reserves the right to change the specifications of its products without prior notice.

CDIL is a registered trademark of Continental Device India Pvt. Limited

C-120 Naraina Industrial Area, New Delhi 110 028, India.

Telephone +91-11-2579 6150, 4141 1112 Fax +91-11-2579 5290, 4141 1119

email@cdil.com www.cdil.com

CIN No. U32109DL1964PTC004291